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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)

Complete if Known

Application Number	10/728,671
Filing Date	12-5-03
First Named Inventor	THOMAS M. MORRIS
Art Unit	2879
Examiner Name	
Attorney Docket Number	

Sheet of **U. S. PATENT DOCUMENTS**

Examiner Initials*	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code ² (if known)			
		US- 4628 422	12-9-86	EWALD	
		US- 4729 076	3-1-88	MASAMI	
		US- 4742 432	5-3-88	THILLAYS	
		US- 4935 665	6-19-90	MURATA	
		US- 5528 474	6-18-96	RDNEY	
		US- 5632 551	5-27-97	RDNEY	
		US- 5782 555	7-21-98	HOCHSTEIN	
		US- 5785 418	7-28-98	HOCHSTEIN	
		US- 5857 767	1-12-99	HOCHSTEIN	
		US- 6016 038	1-18-00	MUELLER	
		US- 6045 240	4-4-00	HOCHSTEIN	
		US- 6161 910	12-19-00	REISENAUER	
		US- 6435 459	8-20-02	SANDERSON	
		US- 6480 389	11-12-02	SHIE	
		US- 6582 100	6-24-03	HOCHSTEIN	
		US- 6517 218	2-11-03	HOCHSTEIN	
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FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages Or Relevant Figures Appear	T ⁵
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of

Thomas M. Morris

Serial Number 10/728,671

Filed: 12/5/03

For: LIGHT EMITTING ASSEMBLY WITH HEAT DISSIPATING SUPPORT

Prior Art Statement

Commissioner of Patents
P. O. Box 1450
Arlington, Virginia 22203

Dear Sir:

Applicant is aware of the following prior art:

1. Ewald U.S. Patent 4,628,422 discloses an LED assembly in which LEDs are mounted in dimples in an anodized aluminum substrate whereby the anodized coating reflects light from the LED.

2. Masami U.S. Patent 4,729,076 discloses an LED assembly in which a plurality of LEDs are attached to a circuit board which is secured to a metal heat sink.

3. Thillays U.S. Patent 4,742,432 discloses an LED assembly using an anodized aluminum substrate having thermal conducting pins extending through the substrate and in contact with the LEDs.

4. Murata U.S. Patent 4,935,665 disclose an LED assembly in which an epoxy layer is bonded to an aluminum substrate, LED's are placed in dimples in the substrate and connected together by wires.

5. Roney U.S. Patent 5,528,474 discloses an LED assembly including a circuit board supporting a plurality of LEDs, the circuit board being in contact with a heat sink.

6. Roney U.S. Patent 5,632,551 discloses an LED assembly including a circuit board supporting a plurality of LEDs, the circuit board being in contact with a heat sink.

7. Hochstein U.S. Patent 5,782,555 discloses an LED assembly including a metal substrate in which the LED's are in thermal contact with the substrate through a thermally conductive adhesive.

8. Hochstein U.S. Patent 5,785,418 discloses an LED assembly including a circuit board in heat transmitting relation to a heat sink.

9. Hochstein U.S. Patent 5,857,767 discloses an LED assembly including a metal substrate in which the LED's are in thermal contact with the substrate through a thermally conductive adhesive and an electrically insulating layer.

10. Mueller U.S. Patent 6,016,038 discloses an LED assembly having multicolor LEDs.

11. Hockstein U.S. Patent 6,045,240 discloses an LED assembly including a circuit board supporting a plurality of LEDs bonded by a thermally conductive adhesive to a heat sink.

12. Reisenauer U.S. Patent 6,161,910 discloses an LED reading light including a circuit board supporting a plurality of LEDs attached to a heat sink.

13. Sanderson U.S. Patent 6,435,459 discloses an LED assembly including a circuit board supporting a plurality of LEDs in thermal contact with a heat sink.

14. Shie U.S. Patent 6,480,389 discloses an LED mounted in a depression filled with a heat transferring liquid.

15. Hockstein U.S. Patent 6,517,218 discloses an LED supported on a circuit board in thermal contact with a heat sink and a heat sink extension extending away from the heat sink into contact with the LED.

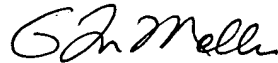
16. Hockstein U.S. Patent 6,582,100 discloses an LED mounted on a circuit board which is in contact with an aluminum heat sink.

A copy of each of the above is attached.

For some years, applicant's assignee has been manufacturing an air conditioning fan motor controller having an anodized aluminum substrate which functions as a heat sink. Circuit traces are

screen printed onto the substrate into a pattern that provides a number of resistors ending at terminals on the edge of the substrate. The ink used is a silver-glass mixture available from Metech Polymers, Elverson, Pennsylvania, known as Metech 3270. Connections are soldered to the terminals to attach the motor controller to a circuit which includes a power source. Using a speed control switch, the resistors are placed in circuit with the fan motor to control its speed.

Respectfully submitted,



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